

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S71	14447	(chip adj on adj board) or cob	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 15:59
S72	11204	S71 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:19
S73	378	S72 and ((side with surface) same (chip or die))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:12
S74	1	S72 and ((side with surface) same (incline))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:13
S75	30	S72 and ((side with surface) same (inclin\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:14
S76	23	S72 and ((side with surface) same (slop\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:15
S77	20	S76 not S75	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:14
S78	3	S72 and ((side with (chip or die)) same (inclin\$3 or slop\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:44
S79	216	endo with tsuneo	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:23

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S80	189	S79 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:24
S81	458	nobuaki with hashimoto	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:24
S82	314	S81 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:50
S83	185	S82 and (chip or die) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 16:25
S84	17	S72 and ((chip or die) same (bevel\$2 or chamfer\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:13
S85	609	(257/620).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/03/24 16:49
S86	398	S85 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:13
S87	7546	((chip or die) same (bevel\$2 or chamfer\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:14
S88	5922	S87 and @ad<"20030313"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:13
S89	3465	S88 and (((chip or die) with (bevel\$2 or chamfer\$2)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:15

## EAST Search History

S90	102	S89 and (interconnect) and insulat\$3 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:28
S91	1425	S89 and ((packag\$3 or stack\$3 or mount\$3) same (chip or die))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/24 17:29